

## Description

The 74AHC1G00Q is an automotive compliant single, two-input positive NAND gate with a standard push-pull output. The device is designed for operation with a power supply range of 2.0V to 5.5V. The gate performs the positive Boolean function:

$$Y = \overline{A \cdot B} \quad \text{or} \quad Y = \overline{A} + \overline{B}$$

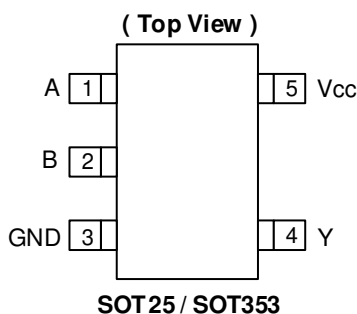
## Features

- Grade 1 Ambient Temperature Operation: -40°C to +125°C
- Supply Voltage Range from 2.0V to 5.5V
- ±8mA Output Drive at 4.5V
- CMOS Low-Power Consumption
- Schmitt Trigger Action at All Inputs Make the Circuit Tolerant for Slower Input Rise and Fall Time
- Inputs not Limited by V<sub>CC</sub>
- Balanced Propagation Delays
- Balanced Drive Capability
- ESD Protection Tested per AEC-Q100
- Exceeds 2000-V Human Body Model (AEC-Q100-002)
- Exceeds 1000-V Charged Device Model (AEC-Q100-011)
- Latch-Up Exceeds 100mA (AEC-Q100-004)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The 74AHC1G00Q is suitable for automotive applications requiring specific change control; this part is AEC-Q100 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

## Pin Assignments



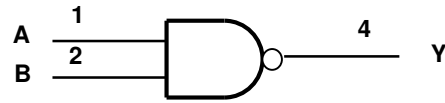
## Applications

- General Purpose Logic
- Wide Array of Products, such as:
  - Automotive Applications within Grade 1 Temperature Range
  - Industrial Computing/Controls/Automation
  - High Reliability Networking/Communications
  - Industrial/Agricultural Equipment

**Pin Descriptions**

Pin Name	Description
A	Data Input
B	Data Input
GND	Ground
Y	Data Output
Vcc	Supply Voltage

**Logic Diagram**



**Function Table**

Inputs		Output
A	B	Y
H	H	L
L	X	H
X	L	H

**Absolute Maximum Ratings** (Notes 4 & 5)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
V <sub>I</sub>	Input Voltage Range	-0.5 to 6.5	V
V <sub>O</sub>	Voltage Applied to Output in High or Low State	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0	-20	mA
I <sub>OK</sub>	Output Clamp Current (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20	mA
I <sub>O</sub>	Continuous Output Current (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±25	mA
I <sub>CC</sub>	Continuous Current Through V <sub>CC</sub>	75	mA
I <sub>GND</sub>	Continuous Current Through GND	-75	mA
T <sub>J</sub>	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>D</sub>	Total Power Dissipation (Note 6)	250	mW

- Notes:
- Stresses beyond the absolute maximum can result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
  - Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.
  - This will need to be derated at higher operating temperatures to prevent exceeding maximum T<sub>J</sub>. Refer to package thermal characteristics section.

**Recommended Operating Conditions** (Note 7)

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	Operating Voltage	—	2	5.5	V
V <sub>IH</sub>	High-Level Input Voltage	V <sub>CC</sub> = 2V	1.5	—	V
		V <sub>CC</sub> = 3V	2.1	—	
		V <sub>CC</sub> = 5.5V	3.85	—	
V <sub>IL</sub>	Low-Level Input Voltage	V <sub>CC</sub> = 2V	—	0.5	V
		V <sub>CC</sub> = 3V	—	0.9	
		V <sub>CC</sub> = 5.5V	—	1.65	
V <sub>I</sub>	Input Voltage	0	5.5	V	
V <sub>O</sub>	Output Voltage	0	V <sub>CC</sub>	V	
I <sub>OH</sub>	High-Level Output Current	V <sub>CC</sub> = 2V	—	-50	μA
		V <sub>CC</sub> = 3.3V ± 0.3V	—	-4	mA
		V <sub>CC</sub> = 5V ± 0.5V	—	-8	
I <sub>OL</sub>	Low-Level Output Current	V <sub>CC</sub> = 2V	—	50	μA
		V <sub>CC</sub> = 3.3V ± 0.3V	—	4	mA
		V <sub>CC</sub> = 5V ± 0.5V	—	8	
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 3.3V ± 0.3V	—	100	ns/V
		V <sub>CC</sub> = 5V ± 0.5V	—	20	
T <sub>A</sub>	Ambient Temperature	—	-40	+125	°C

Note: 7. Unused inputs should be held at V<sub>CC</sub> or Ground.

**Electrical Characteristics** (All typical values are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = +25°C)

Symbol	Parameter	Test Conditions	V <sub>CC</sub>	+25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V <sub>OH</sub>	High Level Output Voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -50μA	2V	1.9	2	—	1.9	—	1.9	—	V
			3V	2.9	3	—	2.9	—	2.9	—	
			4.5V	4.4	4.5	—	4.4	—	4.4	—	
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -4mA	3V	2.58	—	—	2.48	—	2.40	—	
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -8mA	4.5V	3.94	—	—	3.80	—	3.70	—	
V <sub>OL</sub>	Low Level Output Voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 50μA	2V	—	—	0.1	—	0.1	—	0.1	V
			3V	—	—	0.1	—	0.1	—	0.1	
			4.5V	—	—	0.1	—	0.1	—	0.1	
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 4mA	3V	—	—	0.36	—	0.44	—	0.55	
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 8mA	4.5V	—	—	0.36	—	0.44	—	0.55	
I <sub>I</sub>	Input Current	V <sub>I</sub> = 5.5V or GND	0 to 5.5V	—	—	±0.1	—	±1	—	±2	μA
I <sub>CC</sub>	Supply Current	V <sub>I</sub> = 5.5V or GND I <sub>O</sub> = 0	5.5V	—	—	1	—	10	—	40	μA
C <sub>I</sub>	Input Capacitance	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5V	—	1.5	10	—	10	—	10	pF

## Package Characteristics

Symbol	Parameter	Package	Test Conditions	Min	Typ	Max	Unit
$\theta_{JA}$	Thermal Resistance Junction-to-Ambient	SOT25	Note 8	—	184	—	°C/W
		SOT353		—	385	—	
$\theta_{JC}$	Thermal Resistance Junction-to-Case	SOT25	Note 8	—	62	—	°C/W
		SOT353		—	164	—	

Note: 8. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

## Switching Characteristics

$V_{CC} = 3.3V \pm 0.3V$  (See Figure 1)

Parameter	From (Input)	To (Output)	Test Conditions	+25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
$t_{PD}$	A or B	Y	$C_L = 15pF$	1.0	4.5	7.9	1.0	9.5	1.0	10.5	ns
			$C_L = 50pF$	1.0	6.5	11.4	1.0	13.0	1.0	14.5	ns

$V_{CC} = 5V \pm 0.5V$  (See Figure 1)

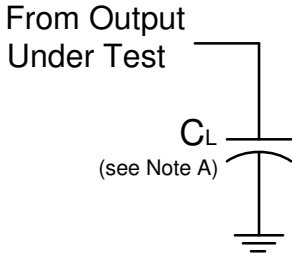
Parameter	From (Input)	To (Output)	Test Conditions	+25°C			-40°C to +85°C		-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
$t_{PD}$	A or B	Y	$C_L = 15pF$	1.0	3.5	5.5	1.0	6.5	1.0	7.0	ns
			$C_L = 50pF$	1.0	4.9	7.5	1.0	8.5	1.0	9.5	ns

## Operating Characteristics

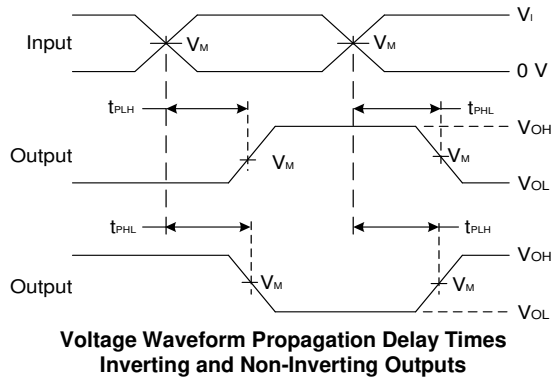
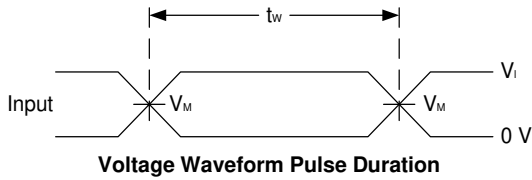
$T_A = +25^\circ C$

Parameter	Test Conditions	$V_{CC} = 5V$		Unit
		Typ		
$C_{PD}$	f = 1MHz No Load	18		pF

**Measurement Information**



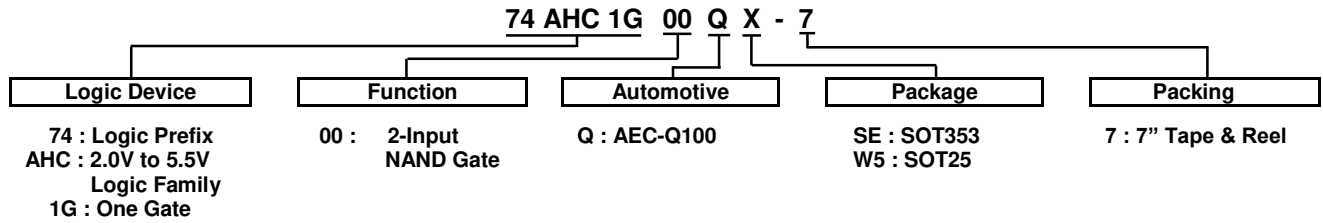
V <sub>CC</sub>	Inputs		V <sub>M</sub>	C <sub>L</sub>
	V <sub>I</sub>	t <sub>R</sub> /t <sub>F</sub>		
3.3V±0.3V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	15pF
5V±0.5V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	15pF
3.3V±0.3V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	50pF
5V±0.5V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	50pF



**Figure 1. Load Circuit and Voltage Waveforms**

- Notes:
- A. Includes test lead and test apparatus capacitance.
  - B. All pulses are supplied at pulse repetition rate ≤ 1MHz.
  - C. Inputs are measured separately one transition per measurement.

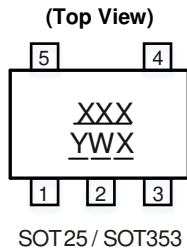
## Ordering Information (Note 9)



Part Number	Package Code	Package (Notes 10 & 11)	Package Size	7" Tape and Reel	
				Quantity	Part Number Suffix
74AHC1G00QSE-7	SE	SOT353	2.15mm × 2.1mm × 1.1mm 0.65mm lead pitch	3000/Tape & Reel	-7
74AHC1G00QW5-7	W5	SOT25	3.0mm × 2.8mm × 1.2mm 0.95mm lead pitch	3000/Tape & Reel	-7

Notes: 9. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.  
 10. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at <http://www.diodes.com/package-outlines.html>.  
 11. The taping orientation is located on our website at <https://www.diodes.com/assets/Packaging-Support-Docs/ap02007.pdf>.

## Marking Information



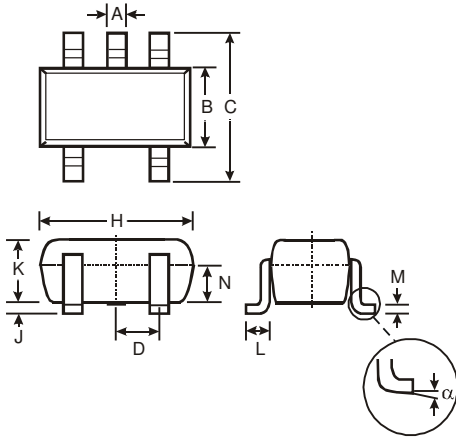
XXX : Identification Code  
 Y : Year 0~9  
 W : Week : A~Z 1~26 week  
       a~z 27~52 week  
       z represents week 52 and 53  
 X : A~Z : Internal Code

Part Number	Package	Identification Code
74AHC1G00QW5-7	SOT25	YRQ
74AHC1G00QSE-7	SOT353	YRQ

## Package Outline Dimensions

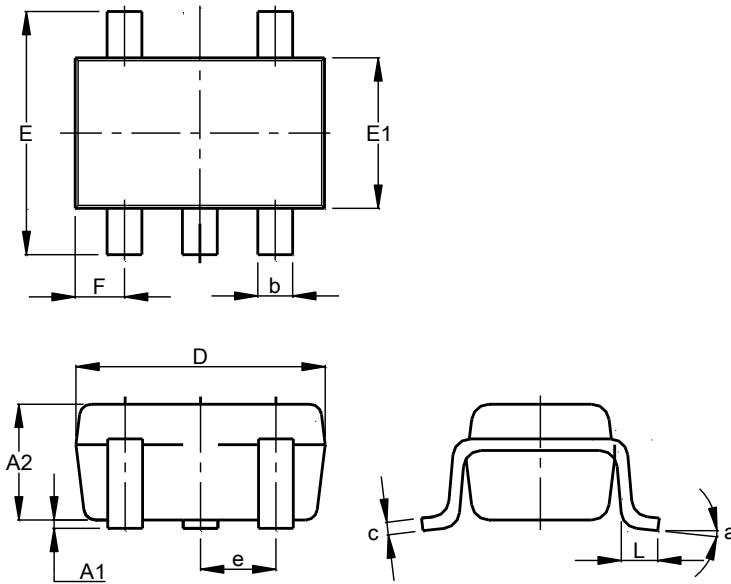
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### (1) Package Type: SOT25



SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
$\alpha$	0°	8°	-
All Dimensions in mm			

### (2) Package Type: SOT353

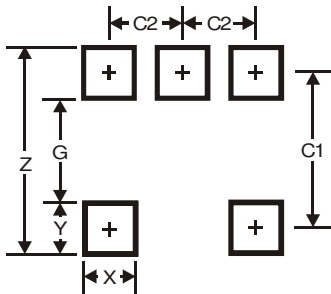


SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

## Suggested Pad Layout

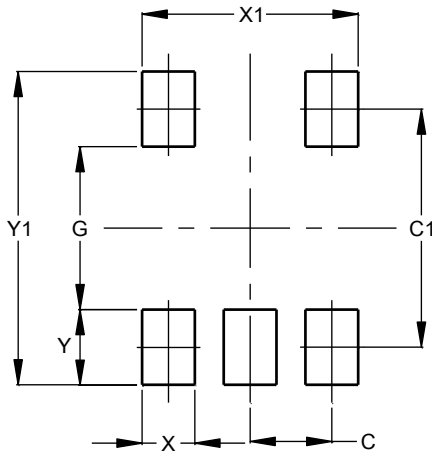
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### (1) Package Type: SOT25



Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

### (2) Package Type: SOT353



Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

## Mechanical Data

### SOT25

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208@3
- Weight: 0.0158 grams (Approximate)

### SOT353

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208@3
- Weight: 0.0064 grams (Approximate)



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